SN74AVCH8T245 8 ビット デュアル電源 バス トランシーバ、構成可能レベルシフト、電圧変換、3 ステート出力

1 特長

- 制御入力 (DIR および $\overline{OE}$) の V_{IH} および V_{IL} レベルは V_{CCA} 電圧を基準
- データ入力時のバス ホールドにより、外付けのプルアップまたはプルダウン抵抗が不要
- V_{CC} 絶縁機能
- 完全に構成可能なデュアル レール設計
- 4.6V 許容の I/O
- I_{off} により部分的パワーダウン モードでの動作をサポート
- 最大データ レート:
  - 320Mbps (V_{CCA} ≥ 1.8V および V_{CCB} ≥ 1.8V)
  - 170Mbps (V_{CCA} ≤ 1.8V または V_{CCB} ≤ 1.8V)
- JESD 78、Class II 準拠で 100mA 超のラッチアップ性能
- JESD 22 を上回る ESD 保護:
  - 8000V、人体モデル (A114-A)
  - マシン モデルで 200V (A115-A)
  - 1000V、荷電デバイス モデル (C101)

2 アプリケーション

- パーソナル・エレクトロニクス
- 産業用
- エンタープライズ
- テレコミュニケーション

3 概要

SN74AVCH8T245 は、設定可能な 2 本の独立した電源レールを採用した 8 ビット非反転バス トランシーバです。A ポートは V_{CCA} (1.2V～3.6V の任意の電源電圧を入力できます) に追従するように設計されています。同様に B ポートは V_{CCB} (1.2V～3.6V の任意の電源電圧を入力できます) に追従するように設計されています。このため 1.2V、1.5V、1.8V、2.5V、3.3V の任意の電圧ノード間で、低電圧の双方向変換を自在に行うことが可能になります。

SN74AVCH8T245 は、データ バス間の非同期通信用に設計されています。このデバイスは、方向制御 (DIR) 入力の論理レベルに応じて、A バスから B バス、または B バスから A バスへデータを転送します。出力イネーブル ($\overline{OE}$) 入力を使用すると、出力をディセーブルにして、バスを実質的に絶縁できます。

SN74AVCH8T245 の設計では、制御ピン (DIR および $\overline{OE}$) は V_{CCA} を基準としています。

アクティブなバス ホールド回路により、使用されていない、または駆動されていないピンは、有効なロジック状態に保持されます。プルアップ抵抗またはプルダウン抵抗をバス ホールド回路と組み合わせて使用することは推奨しません。

このデバイスは、I_{off} を使用する部分的パワーダウン アプリケーション用の動作が完全に規定されています。I_{off} 回路が出力をディセーブルにするため、デバイスに電流が逆流して損傷に至ることを回避できます。

V_{CC} 絶縁機能により、V_{CCA} または V_{CCB} のいずれかが GND レベルのとき、出力をハイ インピーダンス状態にできます。電源オン側のバス ホールド回路は常にアクティブのままです。

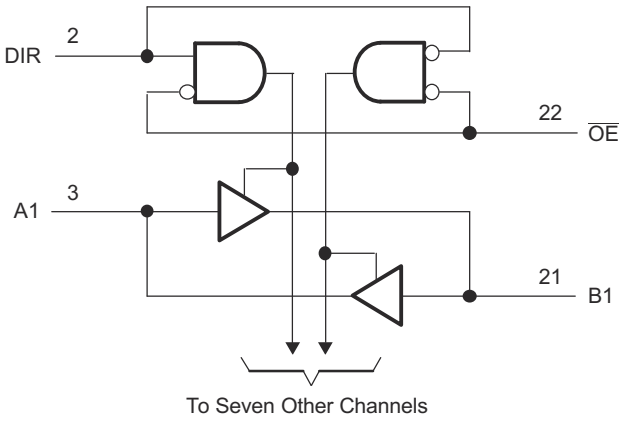
SN74AVCH8T245 ソリューションは単一電源システムと互換性があり、プリント基板の再設計を最小限に抑えながら、後で '245 機能に置き換えることができます。

電源投入時または切断時にデバイスをハイ インピーダンス状態を確保するには、$\overline{OE}$ をプルダウン抵抗で V_{CCA} につなぐ必要があります。この抵抗の最小値は、ドライバの電流ソース能力によって決まります。

パッケージ情報

部品番号	パッケージ (1)	パッケージ サイズ (2)
SN74AVCH8T245	DGV (TVSOP、24)	5 mm × 6.4 mm
	PW (TSSOP、24)	7.8 mm × 6.4 mm
	RHL (VQFN、24)	5.5 mm × 3.5 mm

(1) 詳細については、セクション 11 を参照してください。
(2) パッケージ サイズ (長さ × 幅) は公称値であり、該当する場合はピンも含まれます。



論理図 (正論理)

このリソースの元の言語は英語です。翻訳は概要を便宜的に提供するもので、自動化ツール (機械翻訳) を使用していることがあり、TI では翻訳の正確性および妥当性につきましては一切保証いたしません。実際の設計などの前には、ti.com で必ず最新の英語版をご参照くださいますようお願いいたします。

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4 Pin Configuration and Functions

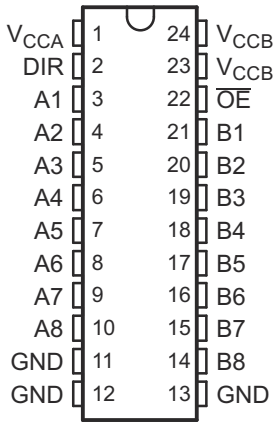

図 4-1. DGV or PW Package, 24-Pin TVSOP or TSSOP (Top View)

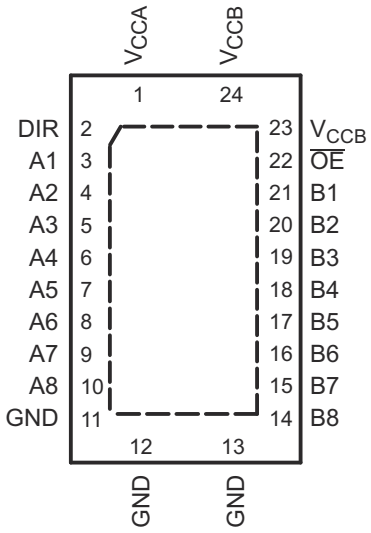

図 4-2. RHL Package, 24-Pin VQFN (Top View)

表 4-1. Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
A1	3	I/O	Input/output A1. Referenced to V_{CCA}.
A2	4	I/O	Input/output A2. Referenced to V_{CCA}.
A3	5	I/O	Input/output A3. Referenced to V_{CCA}.
A4	6	I/O	Input/output A4. Referenced to V_{CCA}.
A5	7	I/O	Input/output A5. Referenced to V_{CCA}.
A6	8	I/O	Input/output A6. Referenced to V_{CCA}.
A7	9	I/O	Input/output A7. Referenced to V_{CCA}.
A8	10	I/O	Input/output A8. Referenced to V_{CCA}.
B1	21	I/O	Input/output B1. Referenced to V_{CCB}.
B2	20	I/O	Input/output B2. Referenced to V_{CCB}.
B3	19	I/O	Input/output B3. Referenced to V_{CCB}.
B4	18	I/O	Input/output B4. Referenced to V_{CCB}.
B5	17	I/O	Input/output B5. Referenced to V_{CCB}.
B6	16	I/O	Input/output B6. Referenced to V_{CCB}.
B7	15	I/O	Input/output B7. Referenced to V_{CCB}.
B8	14	I/O	Input/output B8. Referenced to V_{CCB}.
DIR	2	I	Direction-control signal. Referenced to V_{CCA}.
GND	11, 12, 13	—	Ground
$\overline{OE}$	22	I	3-state output-mode enables. Pull $\overline{OE}$ high to place all outputs in 3-state mode. Referenced to V_{CCA}.
V_{CCA}	1	—	A-port supply voltage. 1.2V ≤ V_{CCA} ≤ 3.6V
V_{CCB}	23, 24	—	B-port supply voltage. 1.2V ≤ V_{CCA} ≤ 3.6V

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5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CCA} V_{CCB}	Supply voltage		–0.5	4.6	V
V_I	Input voltage(2)	I/O ports (A port)	–0.5	4.6	V
		I/O ports (B port)	–0.5	4.6	
		Control inputs	–0.5	4.6	
V_O	Voltage applied to any output in the high-impedance or power-off state(2)	A port	–0.5	4.6	V
		B port	–0.5	4.6	
V_O	Voltage applied to any output in the high or low state(2) (3)	A port	–0.5	V_{CCA} + 0.5	V
		B port	–0.5	V_{CCB} + 0.5	
I_{IK}	Input clamp current	V_I < 0		–50	mA
I_{OK}	Output clamp current	V_O < 0		–50	mA
I_O	Continuous output current			±50	mA
	Continuous current through V_{CCA}, V_{CCB}, or GND			±100	mA
T_J	Junction temperature		–40	150	°C
T_{stg}	Storage temperature		–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input voltage and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
(3) The output positive-voltage rating may be exceeded up to 4.6V maximum if the output current rating is observed.
(4) The package thermal impedance is calculated in accordance with JESD 51-7.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±8000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±1000	
		Machine model (MM)	±200	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

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5.3 Recommended Operating Conditions

See (1) (2)

				MIN	MAX	UNIT
V_{CCA}	Supply voltage			1.2	3.6	V
V_{CCB}	Supply voltage			1.2	3.6	V
V_{IH}	High-level input voltage(1)	Data inputs	V_{CCI} = 1.2V to 1.95V	V_{CCI} × 0.65		V
			V_{CCI} = 1.95V to 2.7V	1.6		
			V_{CCI} = 2.7V to 3.6V	2		
V_{IL}	Low-level input voltage(1)	Data inputs	V_{CCI} = 1.2V to 1.95V		V_{CCI} × 0.35	V
			V_{CCI} = 1.95V to 2.7V		0.7	
			V_{CCI} = 2.7V to 3.6V		0.8	
V_{IH}	High-level input voltage	DIR and $\overline{OE}$ (referenced to V_{CCA})	V_{CCI} = 1.2V to 1.95V	V_{CCA} × 0.65		V
			V_{CCI} = 1.95V to 2.7V	1.6		
			V_{CCI} = 2.7V to 3.6V	2		
V_{IL}	Low-level input voltage	DIR and $\overline{OE}$ (referenced to V_{CCA})	V_{CCI} = 1.2V to 1.95V		V_{CCA} × 0.35	V
			V_{CCI} = 1.95V to 2.7V		0.7	
			V_{CCI} = 2.7V to 3.6V		0.8	
V_I	Input voltage	Control Inputs		0	3.6	V
V_O	Output voltage(2)	Active state		0	V_{CCO}	V
		3-state		0	3.6	
I_{OH}	High-level output current		V_{CCO} = 1.2V		–3	mA
			V_{CCO} = 1.4V to 1.6V		–6	
			V_{CCO} = 1.65V to 1.95V		–8	
			V_{CCO} = 2.3V to 2.7V		–9	
			V_{CCO} = 3V to 3.6V		–12	
I_{OL}	Low-level output current		V_{CCO} = 1.2V		3	mA
			V_{CCO} = 1.4V to 1.6V		6	
			V_{CCO} = 1.65V to 1.95V		8	
			V_{CCO} = 2.3V to 2.7V		9	
			V_{CCO} = 3V to 3.6V		12	
Δt/Δv	Input transition rise or fall rate				5	ns/V
T_A	Operating free-air temperature			–40	85	°C

(1) V_{CCI} is the V_{CC} associated with the input port.
(2) V_{CCO} is the V_{CC} associated with the output port.

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5.4 Thermal Information

THERMAL METRIC(1)		SN74AVCH8T245			UNIT
		DGV (TVSOP)	PW (TSSOP)	RHL (VQFN)	
		24 PINS	24 PINS	24 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance(4)	116.7	93.1	36.8	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	48.5	36.7	32.5	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	62.1	48.4	15.7	°C/W
ψ_{JT}	Junction-to-top characterization parameter	7.0	93.1	0.7	°C/W
ψ_{JB}	Junction-to-board characterization parameter	61.6	48.0	15.6	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	5.6	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, SPRA953.

5.5 Electrical Characteristics

All typical limits apply over T_A = 25°C, and all maximum and minimum limits apply over T_A = –40°C to 85°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage(1)	I_{OH} = –100µA, V_I= V_{IH}	V_{CCA} = V_{CCB} = 1.2V to 3.6V	V_{CCO} – 0.2			V
		I_{OH} = –3mA, V_I= V_{IH}	V_{CCA} = V_{CCB} = 1.2V		0.95		
		I_{OH} = –6mA, V_I= V_{IH}	V_{CCA} = V_{CCB} = 1.4V	1.05			
		I_{OH} = –8mA, V_I= V_{IH}	V_{CCA} = V_{CCB} = 1.65V	1.2			
		I_{OH} = –9mA, V_I= V_{IH}	V_{CCA} = V_{CCB} = 2.3V	1.75			
		I_{OH} = –12mA, V_I= V_{IH}	V_{CCA} = V_{CCB} = 3V	2.3			
V_{OL}	Low-level output voltage	I_{OL} = 100µA, V_I= V_{IL}	V_{CCA} = V_{CCB} = 1.2V to 3.6V			0.2	V
		I_{OL} = 3mA, V_I= V_{IL}	V_{CCA} = V_{CCB} = 1.2V		0.15		
		I_{OL} = 6mA, V_I= V_{IL}	V_{CCA} = V_{CCB} = 1.4V			0.35	
		I_{OL} = 8mA, V_I= V_{IL}	V_{CCA} = V_{CCB} = 1.65V			0.45	
		I_{OL} = 9mA, V_I= V_{IL}	V_{CCA} = V_{CCB} = 2.3V			0.55	
		I_{OL} = 12mA, V_I= V_{IL}	V_{CCA} = V_{CCB} = 3V			0.7	
I_I	Control inputs	V_I = V_{CCA} or GND	V_{CCA} = V_{CCB} = 1.2V to 3.6V		±0.025	±1	µA
I_{BHL}	Bus-hold low sustaining current(5)	V_I = 0.42V	V_{CCA} = V_{CCB} = 1.2V		25		µA
		V_I = 0.49V	V_{CCA} = V_{CCB} = 1.4V	15			
		V_I = 0.58V	V_{CCA} = V_{CCB} = 1.65V	25			
		V_I = 0.7V	V_{CCA} = V_{CCB} = 2.3V	45			
		V_I = 0.8V	V_{CCA} = V_{CCB} = 3.3V	100			
I_{BHH}	Bus-hold high sustaining current(6)	V_I = 0.78V	V_{CCA} = V_{CCB} = 1.2V		–25		µA
		V_I = 0.91V	V_{CCA} = V_{CCB} = 1.4V	–15			
		V_I = 1.07V	V_{CCA} = V_{CCB} = 1.65V	–25			
		V_I = 1.6V	V_{CCA} = V_{CCB} = 2.3V	–45			
		V_I = 2V	V_{CCA} = V_{CCB} = 3.3V	–100			
I_{BHLO}	Bus-hold low overdrive current(3)	V_I = 0 to V_{CC}	V_{CCA} = V_{CCB} = 1.2V		50		µA
			V_{CCA} = V_{CCB} = 1.6V	125			
			V_{CCA} = V_{CCB} = 1.95V	200			
			V_{CCA} = V_{CCB} = 2.7V	300			
			V_{CCA} = V_{CCB} = 3.6V	500			

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5.5 Electrical Characteristics (続き)

All typical limits apply over T_A = 25°C, and all maximum and minimum limits apply over T_A = –40°C to 85°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
I_{BHHO}	Bus-hold high overdrive current(4)	V_I = 0 to V_{CC}	V_{CCA} = V_{CCB} = 1.2V			–50		μA
			V_{CCA} = V_{CCB} = 1.6V		–125			
			V_{CCA} = V_{CCB} = 1.95V		–200			
			V_{CCA} = V_{CCB} = 2.7V		–300			
			V_{CCA} = V_{CCB} = 3.6V		–500			
I_{off}	Input/output power-off leakage current	V_I = 0V to 3.6V, V_O= 0V to 3.6V	V_{CCA} = 0V, V_{CCB} = 0V to 3.6V	A Port		±0.1	±5	μA
			V_{CCA} = 0V to 3.6V, V_{CCB} = 0V	B Port		±0.1	±5	
I_{OZ}	Off-state output current (1) (2) (7)	V_O = V_{CCO} or GND, V_I = V_{CCI} or GND, $\overline{OE}$ = V_{IH}	V_{CCA} = V_{CCB} = 3.6V	A Port, B Port		±0.5	±5	μA
		V_O = V_{CCO} or GND, V_I = V_{CCI} or GND, $\overline{OE}$ = Don't Care	V_{CCA} = 0V, V_{CCB} = 3.6V	B Port			±5	
			V_{CCA} = 3.6V, V_{CCB} = 0V	A Port			±5	
I_{CCA}	Supply current A port(2)	V_I = V_{CCI} or GND, I_O = 0	V_{CCA} = V_{CCB} = 1.2V to 3.6V				8	μA
			V_{CCA} = 0V, V_{CCB} = 3.6V				–2	
			V_{CCA} = 3.6V, V_{CCB} = 0V				8	
I_{CCB}	Supply current B port(2)	V_I = V_{CCI} or GND, I_O = 0	V_{CCA} = V_{CCB} = 1.2V to 3.6V				8	μA
			V_{CCA} = 0V, V_{CCB} = 3.6V				8	
			V_{CCA} = 3.6V, V_{CCB} = 0V				–2	
I_{CCA}+ I_{CCB}	Combined supply current(2)	V_I = V_{CCI} or GND, I_O = 0	V_{CCA} = V_{CCB} = 1.2V to 3.6V				16	μA
C_i	Input capacitance control pins	V_I = 3.3V or GND	V_{CCA} = V_{CCB} = 3.3V			3.5	4.5	pF
C_{io}	Input/output capacitance a or b port	V_O = 3.3V or GND	V_{CCA} = V_{CCB} = 3.3V			6	7	pF

(1) V_{CCO} is the V_{CC} associated with the output port.
(2) V_{CCI} is the V_{CC} associated with the input port.
(3) An external driver must source at least I_{BHLO} to switch this node from low to high.
(4) An external driver must sink at least I_{BHHO} to switch this node from high to low.
(5) The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.
(6) The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.
(7) For I/O ports, the parameter I_{OZ} includes the input leakage current.

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5.6 Switching Characteristics, V_{CCA} = 1.2V

T_A= 25°C (see 図 6-1)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}, t_{PHL}	Propagation delay time: low-to-high-level output and high-to-low level output	A	B	V_{CCB} = 1.2V		3.1		ns
				V_{CCB} = 1.5V		2.6		
				V_{CCB} = 1.8V		2.5		
				V_{CCB} = 2.5V		3		
				V_{CCB} = 3.3V		3.5		
t_{PLH}, t_{PHL}	Propagation delay time: low-to-high-level output and high-to-low level output	B	A	V_{CCB} = 1.2V		3.1		ns
				V_{CCB} = 1.5V		2.7		
				V_{CCB} = 1.8V		2.5		
				V_{CCB} = 2.5V		2.4		
				V_{CCB} = 3.3V		2.3		
t_{PZH}, t_{PZL}	Enable time: to high level and to low level	$\overline{OE}$	A	V_{CCB} = 1.2V		5.3		ns
				V_{CCB} = 1.5V		5.3		
				V_{CCB} = 1.8V		5.3		
				V_{CCB} = 2.5V		5.3		
				V_{CCB} = 3.3V		5.3		
t_{PZH}, t_{PZL}	Enable time: to high level and to low level	$\overline{OE}$	B	V_{CCB} = 1.2V		5.1		ns
				V_{CCB} = 1.5V		4		
				V_{CCB} = 1.8V		3.5		
				V_{CCB} = 2.5V		3.2		
				V_{CCB} = 3.3V		3.1		
t_{PHZ}, t_{PLZ}	Disable time: from high level and from low level	$\overline{OE}$	A	V_{CCB} = 1.2V		4.8		ns
				V_{CCB} = 1.5V		4.8		
				V_{CCB} = 1.8V		4.8		
				V_{CCB} = 2.5V		4.8		
				V_{CCB} = 3.3V		4.8		
t_{PHZ}, t_{PLZ}	Disable time: from high level and from low level	$\overline{OE}$	B	V_{CCB} = 1.2V		4.7		ns
				V_{CCB} = 1.5V		4		
				V_{CCB} = 1.8V		4.1		
				V_{CCB} = 2.5V		4.3		
				V_{CCB} = 3.3V		5.1		

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5.7 Switching Characteristics, V_{CCA}= 1.5V ± 0.1V

All typical limits apply over T_A = 25°C, and all maximum and minimum limits apply over T_A = –40°C to 85°C (unless otherwise noted) (see 図 6-1)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}, t_{PHL}	Propagation delay time: low-to-high-level output and high-to-low level output	A	B	V_{CCB} = 1.2V		2.7		ns
				V_{CCB} = 1.5V	0.5		5.4	
				V_{CCB} = 1.8V	0.5		4.6	
				V_{CCB} = 2.5V	0.5		4.9	
				V_{CCB} = 3.3V	0.5		6.8	
t_{PLH}, t_{PHL}	Propagation delay time: low-to-high-level output and high-to-low level output	B	A	V_{CCB} = 1.2V		2.6		ns
				V_{CCB} = 1.5V	0.5		5.4	
				V_{CCB} = 1.8V	0.5		5.1	
				V_{CCB} = 2.5V	0.5		4.7	
				V_{CCB} = 3.3V	0.5		4.5	
t_{PZH}, t_{PZL}	Enable time: to high level and to low level	$\overline{OE}$	A	V_{CCB} = 1.2V		3.7		ns
				V_{CCB} = 1.5V	1.1		8.7	
				V_{CCB} = 1.8V	1.1		8.7	
				V_{CCB} = 2.5V	1.1		8.7	
				V_{CCB} = 3.3V	1.1		8.7	
t_{PZH}, t_{PZL}	Enable time: to high level and to low level	$\overline{OE}$	B	V_{CCB} = 1.2V		4.8		ns
				V_{CCB} = 1.5V	1.1		7.6	
				V_{CCB} = 1.8V	1.1		7.1	
				V_{CCB} = 2.5V	1.1		5.6	
				V_{CCB} = 3.3V	1.1		5.2	
t_{PHZ}, t_{PLZ}	Disable time: from high level and from low level	$\overline{OE}$	A	V_{CCB} = 1.2V		3.1		ns
				V_{CCB} = 1.5V	0.5		8.6	
				V_{CCB} = 1.8V	0.5		8.6	
				V_{CCB} = 2.5V	0.5		8.6	
				V_{CCB} = 3.3V	0.5		8.6	
t_{PHZ}, t_{PLZ}	Disable time: from high level and from low level	$\overline{OE}$	B	V_{CCB} = 1.2V		4.1		ns
				V_{CCB} = 1.5V	0.5		8.4	
				V_{CCB} = 1.8V	0.5		7.6	
				V_{CCB} = 2.5V	0.5		7.2	
				V_{CCB} = 3.3V	0.5		7.8	

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5.8 Switching Characteristics, V_{CCA}= 1.8V ± 0.15V

All typical limits apply over T_A = 25°C, and all maximum and minimum limits apply over T_A = –40°C to 85°C (unless otherwise noted) (see 図 6-1)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}, t_{PHL}	Propagation delay time: low-to-high-level output and high-to-low level output	A	B	V_{CCB} = 1.2V		2.5		ns
				V_{CCB} = 1.5V	0.5		5.1	
				V_{CCB} = 1.8V	0.5		4.4	
				V_{CCB} = 2.5V	0.5		4	
				V_{CCB} = 3.3V	0.5		3.9	
t_{PLH}, t_{PHL}	Propagation delay time: low-to-high-level output and high-to-low level output	B	A	V_{CCB} = 1.2V		2.5		ns
				V_{CCB} = 1.5V	0.5		4.6	
				V_{CCB} = 1.8V	0.5		4.4	
				V_{CCB} = 2.5V	0.5		3.9	
				V_{CCB} = 3.3V	0.5		3.7	
t_{PZH}, t_{PZL}	Enable time: to high level and to low level	$\overline{OE}$	A	V_{CCB} = 1.2V		3		ns
				V_{CCB} = 1.5V	1		6.8	
				V_{CCB} = 1.8V	1		6.8	
				V_{CCB} = 2.5V	1		6.8	
				V_{CCB} = 3.3V	1		6.8	
t_{PZH}, t_{PZL}	Enable time: to high level and to low level	$\overline{OE}$	B	V_{CCB} = 1.2V		4.6		ns
				V_{CCB} = 1.5V	1.1		8.2	
				V_{CCB} = 1.8V	1		6.7	
				V_{CCB} = 2.5V	0.5		5.1	
				V_{CCB} = 3.3V	0.5		4.5	
t_{PHZ}, t_{PLZ}	Disable time: from high level and from low level	$\overline{OE}$	A	V_{CCB} = 1.2V		2.8		ns
				V_{CCB} = 1.5V	0.5		7.1	
				V_{CCB} = 1.8V	0.5		7.1	
				V_{CCB} = 2.5V	0.5		7.1	
				V_{CCB} = 3.3V	0.5		7.1	
t_{PHZ}, t_{PLZ}	Disable time: from high level and from low level	$\overline{OE}$	B	V_{CCB} = 1.2V		3.9		ns
				V_{CCB} = 1.5V	0.5		7.8	
				V_{CCB} = 1.8V	0.5		6.9	
				V_{CCB} = 2.5V	0.5		6	
				V_{CCB} = 3.3V	0.5		5.8	

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5.9 Switching Characteristics, V_{CCA}= 2.5V ± 0.2V

All typical limits apply over T_A = 25°C, and all maximum and minimum limits apply over T_A = –40°C to 85°C (unless otherwise noted) (see 図 6-1)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}, t_{PHL}	Propagation delay time: low-to-high-level output and high-to-low level output	A	B	V_{CCB} = 1.2V		2.4		ns
				V_{CCB} = 1.5V	0.5		4.7	
				V_{CCB} = 1.8V	0.5		3.9	
				V_{CCB} = 2.5V	0.5		3.1	
				V_{CCB} = 3.3V	0.5		2.8	
t_{PLH}, t_{PHL}	Propagation delay time: low-to-high-level output and high-to-low level output	B	A	V_{CCB} = 1.2V		3		ns
				V_{CCB} = 1.5V	0.5		4.9	
				V_{CCB} = 1.8V	0.5		4	
				V_{CCB} = 2.5V	0.5		3.1	
				V_{CCB} = 3.3V	0.5		2.9	
t_{PZH}, t_{PZL}	Enable time: to high level and to low level	$\overline{OE}$	A	V_{CCB} = 1.2V		2.2		ns
				V_{CCB} = 1.5V	0.5		4.8	
				V_{CCB} = 1.8V	0.5		4.8	
				V_{CCB} = 2.5V	0.5		4.8	
				V_{CCB} = 3.3V	0.5		4.8	
t_{PZH}, t_{PZL}	Enable time: to high level and to low level	$\overline{OE}$	B	V_{CCB} = 1.2V		4.5		ns
				V_{CCB} = 1.5V	1.1		7.9	
				V_{CCB} = 1.8V	0.5		6.4	
				V_{CCB} = 2.5V	0.5		4.6	
				V_{CCB} = 3.3V	0.5		4	
t_{PHZ}, t_{PLZ}	Disable time: from high level and from low level	$\overline{OE}$	A	V_{CCB} = 1.2V		1.8		ns
				V_{CCB} = 1.5V	0.5		5.1	
				V_{CCB} = 1.8V	0.5		5.1	
				V_{CCB} = 2.5V	0.5		5.1	
				V_{CCB} = 3.3V	0.5		5.1	
t_{PHZ}, t_{PLZ}	Disable time: from high level and from low level	$\overline{OE}$	B	V_{CCB} = 1.2V		3.6		ns
				V_{CCB} = 1.5V	0.5		7.1	
				V_{CCB} = 1.8V	0.5		6.3	
				V_{CCB} = 2.5V	0.5		5.1	
				V_{CCB} = 3.3V	0.5		3.9	

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5.10 Switching Characteristics, V_{CCA}= 3.3V ± 0.3V

All typical limits apply over T_A = 25°C, and all maximum and minimum limits apply over T_A = –40°C to 85°C (unless otherwise noted) (see 図 6-1)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}, t_{PHL}	Propagation delay time: low-to-high-level output and high-to-low level output	A	B	V_{CCB} = 1.2V		2.3		ns
				V_{CCB} = 1.5V	0.5		4.5	
				V_{CCB} = 1.8V	0.5		3.7	
				V_{CCB} = 2.5V	0.5		2.9	
				V_{CCB} = 3.3V	0.5		2.5	
t_{PLH}, t_{PHL}	Propagation delay time: low-to-high-level output and high-to-low level output	B	A	V_{CCB} = 1.2V		3.5		ns
				V_{CCB} = 1.5V	0.5		6.8	
				V_{CCB} = 1.8V	0.5		3.9	
				V_{CCB} = 2.5V	0.5		2.8	
				V_{CCB} = 3.3V	0.5		2.5	
t_{PZH}, t_{PZL}	Enable time: to high level and to low level	$\overline{OE}$	A	V_{CCB} = 1.2V		2		ns
				V_{CCB} = 1.5V	0.5		4	
				V_{CCB} = 1.8V	0.5		4	
				V_{CCB} = 2.5V	0.5		4	
				V_{CCB} = 3.3V	0.5		4	
t_{PZH}, t_{PZL}	Enable time: to high level and to low level	$\overline{OE}$	B	V_{CCB} = 1.2V		4.5		ns
				V_{CCB} = 1.5V	1.1		7.8	
				V_{CCB} = 1.8V	0.5		6.2	
				V_{CCB} = 2.5V	0.5		4.5	
				V_{CCB} = 3.3V	0.5		3.9	
t_{PHZ}, t_{PLZ}	Disable time: from high level and from low level	$\overline{OE}$	A	V_{CCB} = 1.2V		1.7		ns
				V_{CCB} = 1.5V	0.5		4	
				V_{CCB} = 1.8V	0.5		4	
				V_{CCB} = 2.5V	0.5		4	
				V_{CCB} = 3.3V	0.5		4	
t_{PHZ}, t_{PLZ}	Disable time: from high level and from low level	$\overline{OE}$	B	V_{CCB} = 1.2V		3.4		ns
				V_{CCB} = 1.5V	0.5		6.9	
				V_{CCB} = 1.8V	0.5		6	
				V_{CCB} = 2.5V	0.5		4.8	
				V_{CCB} = 3.3V	0.5		4.2	

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5.11 Operating Characteristics

T_A= 25°C

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		TYP	UNIT
C_{pdA}	Power dissipation capacitance per transceiver[1] port A - outputs enabled	A	B	C_L = 0pF, f = 10MHz, t_r = t_f = 1ns	V_{CCA} = V_{CCB} = 1.2V	1	pF
					V_{CCA} = V_{CCB} = 1.5V	1	
					V_{CCA} = V_{CCB} = 1.8V	1	
					V_{CCA} = V_{CCB} = 2.5V	1	
					V_{CCA} = V_{CCB} = 3.3V	1	
	Power dissipation capacitance per transceiver[1] port A - outputs disabled	A	B	C_L = 0pF, f = 10MHz, t_r = t_f = 1ns	V_{CCA} = V_{CCB} = 1.2V	1	
					V_{CCA} = V_{CCB} = 1.5V	1	
					V_{CCA} = V_{CCB} = 1.8V	1	
					V_{CCA} = V_{CCB} = 2.5V	1	
					V_{CCA} = V_{CCB} = 3.3V	1	
	Power dissipation capacitance per transceiver[1] port A - outputs enabled	B	A	C_L = 0pF, f = 10MHz, t_r = t_f = 1ns	V_{CCA} = V_{CCB} = 1.2V	12	
					V_{CCA} = V_{CCB} = 1.5V	12	
					V_{CCA} = V_{CCB} = 1.8V	12	
					V_{CCA} = V_{CCB} = 2.5V	13	
					V_{CCA} = V_{CCB} = 3.3V	14	
	Power dissipation capacitance per transceiver[1] port A - outputs disabled	B	A	C_L = 0pF, f = 10MHz, t_r = t_f = 1ns	V_{CCA} = V_{CCB} = 1.2V	1	
					V_{CCA} = V_{CCB} = 1.5V	1	
					V_{CCA} = V_{CCB} = 1.8V	1	
					V_{CCA} = V_{CCB} = 2.5V	1	
					V_{CCA} = V_{CCB} = 3.3V	1	
C_{pdB}	Power dissipation capacitance per transceiver[1] port B - outputs enabled	A	B	C_L = 0pF, f = 10MHz, t_r = t_f = 1ns	V_{CCA} = V_{CCB} = 1.2V	12	pF
					V_{CCA} = V_{CCB} = 1.5V	12	
					V_{CCA} = V_{CCB} = 1.8V	12	
					V_{CCA} = V_{CCB} = 2.5V	13	
					V_{CCA} = V_{CCB} = 3.3V	14	
	Power dissipation capacitance per transceiver[1] port B - outputs disabled	A	B	C_L = 0pF, f = 10MHz, t_r = t_f = 1ns	V_{CCA} = V_{CCB} = 1.2V	1	
					V_{CCA} = V_{CCB} = 1.5V	1	
					V_{CCA} = V_{CCB} = 1.8V	1	
					V_{CCA} = V_{CCB} = 2.5V	1	
					V_{CCA} = V_{CCB} = 3.3V	1	
	Power dissipation capacitance per transceiver[1] port B - outputs enabled	B	A	C_L = 0pF, f = 10MHz, t_r = t_f = 1ns	V_{CCA} = V_{CCB} = 1.2V	1	
					V_{CCA} = V_{CCB} = 1.5V	1	
					V_{CCA} = V_{CCB} = 1.8V	1	
					V_{CCA} = V_{CCB} = 2.5V	1	
					V_{CCA} = V_{CCB} = 3.3V	1	
	Power dissipation capacitance per transceiver[1] port B - outputs disabled	B	A	C_L = 0pF, f = 10MHz, t_r = t_f = 1ns	V_{CCA} = V_{CCB} = 1.2V	1	
					V_{CCA} = V_{CCB} = 1.5V	1	
					V_{CCA} = V_{CCB} = 1.8V	1	
					V_{CCA} = V_{CCB} = 2.5V	1	
					V_{CCA} = V_{CCB} = 3.3V	1	

(1) See to TI application report, *CMOS Power Consumption and Cpd Calculation* (SCAA035).

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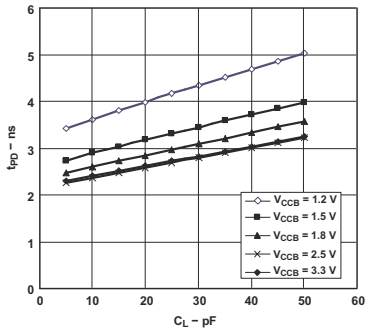
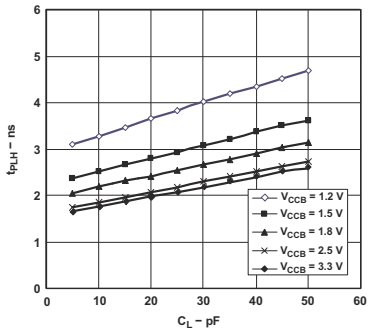
5.12 Typical Characteristics

T_A = 25°C



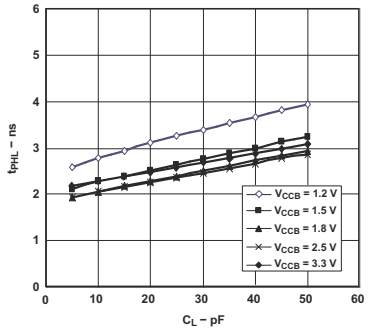
V_{CCA} = 1.2V

図 5-1. Typical Propagation Delay (A to B) vs Load Capacitance



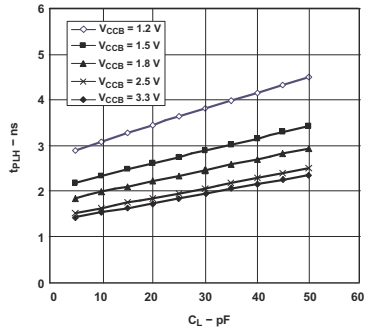
V_{CCA} = 1.5V

図 5-2. Typical Propagation Delay (A to B) vs Load Capacitance



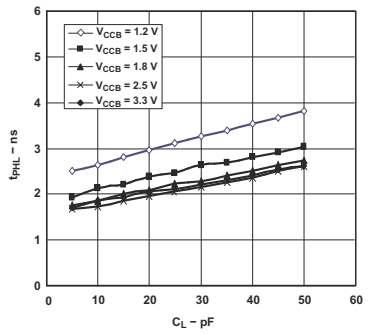
V_{CCA} = 1.5V

図 5-3. Typical Propagation Delay (A to B) vs Load Capacitance



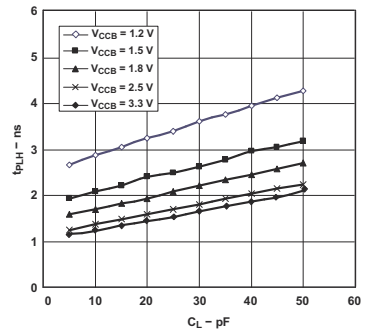
V_{CCA} = 1.8V

図 5-4. Typical Propagation Delay (A to B) vs Load Capacitance



V_{CCA} = 1.8V

図 5-5. Typical Propagation Delay (A to B) vs Load Capacitance



V_{CCA} = 2.5V

図 5-6. Typical Propagation Delay (A to B) vs Load Capacitance

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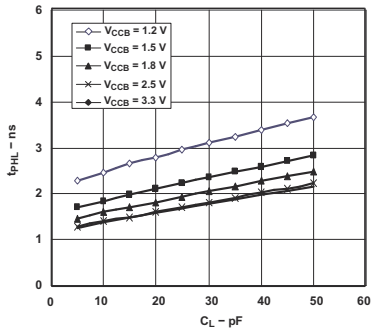
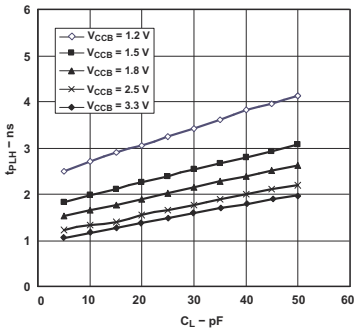
5.12 Typical Characteristics (continued)

T_A = 25°C



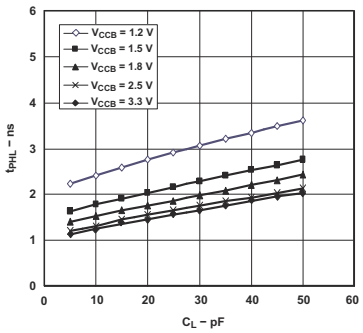
V_{CCA} = 2.5V

図 5-7. Typical Propagation Delay (A to B) vs Load Capacitance



V_{CCA} = 3.3V

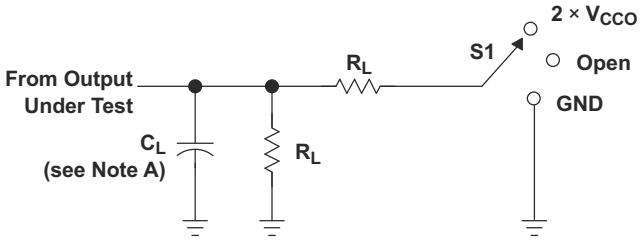
図 5-8. Typical Propagation Delay (A to B) vs Load Capacitance



V_{CCA} = 3.3V

図 5-9. Typical Propagation Delay (A to B) vs Load Capacitance

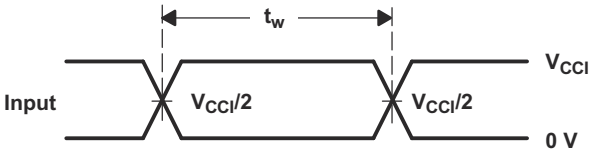
6 Parameter Measurement Information



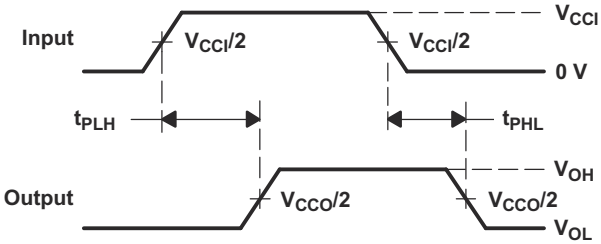
LOAD CIRCUIT

TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open 2 × V_{CCO} GND

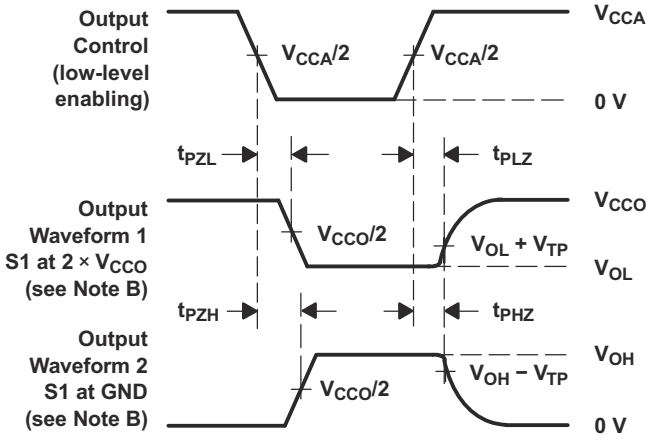
V_{CCO}	C_L	R_L	V_{TP}
1.2 V	15 pF	2 kΩ	0.1 V
1.5 V ± 0.1 V	15 pF	2 kΩ	0.1 V
1.8 V ± 0.15 V	15 pF	2 kΩ	0.15 V
2.5 V ± 0.2 V	15 pF	2 kΩ	0.15 V
3.3 V ± 0.3 V	15 pF	2 kΩ	0.3 V



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50Ω, dv/dt ≥ 1 V/ns.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.
H. V_{CCI} is the V_{CC} associated with the input port.
I. V_{CCO} is the V_{CC} associated with the output port.

図 6-1. Load Circuit and Voltage Waveforms

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7 Detailed Description

7.1 Overview

The SN74AVCH8T245 is an 8-bit, dual supply noninverting bidirectional voltage level translator. Pins A1 through A4, and the control pins (DIR and $\overline{OE}$) are referenced to V_{CCA}, while pins B1 through B4 are referenced to V_{CCB}. Both the A port and B port can accept I/O voltages ranging from 1.2V to 3.6V. With $\overline{OE}$ set to low, a high on DIR allows data transmission from Port A to Port B, and a low on DIR allows data transmission from Port B to Port A. When $\overline{OE}$ is set to high, both Port A and Port B outputs are in the high-impedance state. For more information, see *AVC Logic Family Technology and Application*.

7.2 Functional Block Diagram

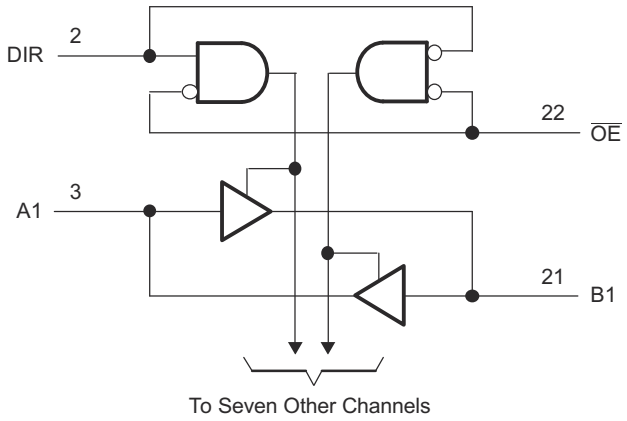

図 7-1. Logic Diagram (Positive Logic)

7.3 Feature Description

7.3.1 Fully Configurable Dual-Rail Design

Both V_{CCA} and V_{CCB} can be supplied at any voltage from 1.2V to 3.6V, making the device an excellent choice for translating between any of the low voltage nodes: 1.2V, 1.8V, 2.5V, and 3.3V.

表 7-1. Typical Total Static Power Consumption (I_{CCA} + I_{CCB})

V_{CCB}	V_{CCA}						UNIT
	0V	1.2V	1.5V	1.8V	2.5V	3.3V	
0V	0	<0.5	<0.5	<0.5	<0.5	<0.5	μA
1.2V	<0.5	<1	<1	<1	<1	1	
1.5V	<0.5	<1	<1	<1	<1	1	
1.8V	<0.5	<1	<1	<1	<1	<1	
2.5V	<0.5	1	<1	<1	<1	<1	
3.3V	<0.5	1	<1	<1	<1	<1	

7.3.2 Supports High-Speed Translation

SN74AVCH8T245 can support high data rate applications, which can be calculated from the maximum propagation delay. This is also dependent on output load. The translated signal data rate can be up to 320Mbps when both V_{CCA} and V_{CCB} are at least 1.8V.

7.3.3 Partial-Power-Down Mode Operation

I_{off} circuitry disables the outputs, preventing damaging current backflow through the SN74AVCH8T245 when it is powered down. Damaging current backflow can occur in applications where subsections of a system are powered down (partial-power-down) to reduce power consumption.

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7.3.4 Bus-Hold Circuitry

Active bus-hold circuitry holds unused or undriven data inputs at a valid logic state, which helps with board space savings and reduced component costs. Use of pull-up or pull-down resistors with the bus-hold circuitry is not recommended. For more information, see *Bus-Hold Circuit*.

7.3.5 V_{CC} Isolation Feature

The V_{CC} isolation feature allows both ports to be in a high-impedance state if either V_{CCA} or V_{CCB} are at GND (or < 0.4V). For more information, see I_{OZ} in the *Electrical Characteristics*. This feature prevents false logic levels from being presented to either bus.

7.4 Device Functional Modes

表 7-2 lists the functional modes of the SN74AVCH8T245.

表 7-2. Function Table (Each 8-Bit Section)

CONTROL INPUTS(1)		OUTPUT CIRCUITS		OPERATION
$\overline{OE}$	DIR	A PORT	B PORT	
L	L	Enabled	Hi-Z	B data to A bus
L	H	Hi-Z	Enabled	A data to B bus
H	X	Hi-Z	Hi-Z	Isolation

(1) Input circuits of the data I/Os are always active.

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8 Application and Implementation

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8.1 Application Information

The SN74AVCH8T245 device can be used in level-translation applications for interfacing devices or systems operating at different interface voltages with one another. The SN74AVCH8T245 device is an excellent choice for data transmission when direction is different. The maximum data rate can be up to 320Mbps when device voltage power supply is more than 1.8V.

8.2 Typical Application

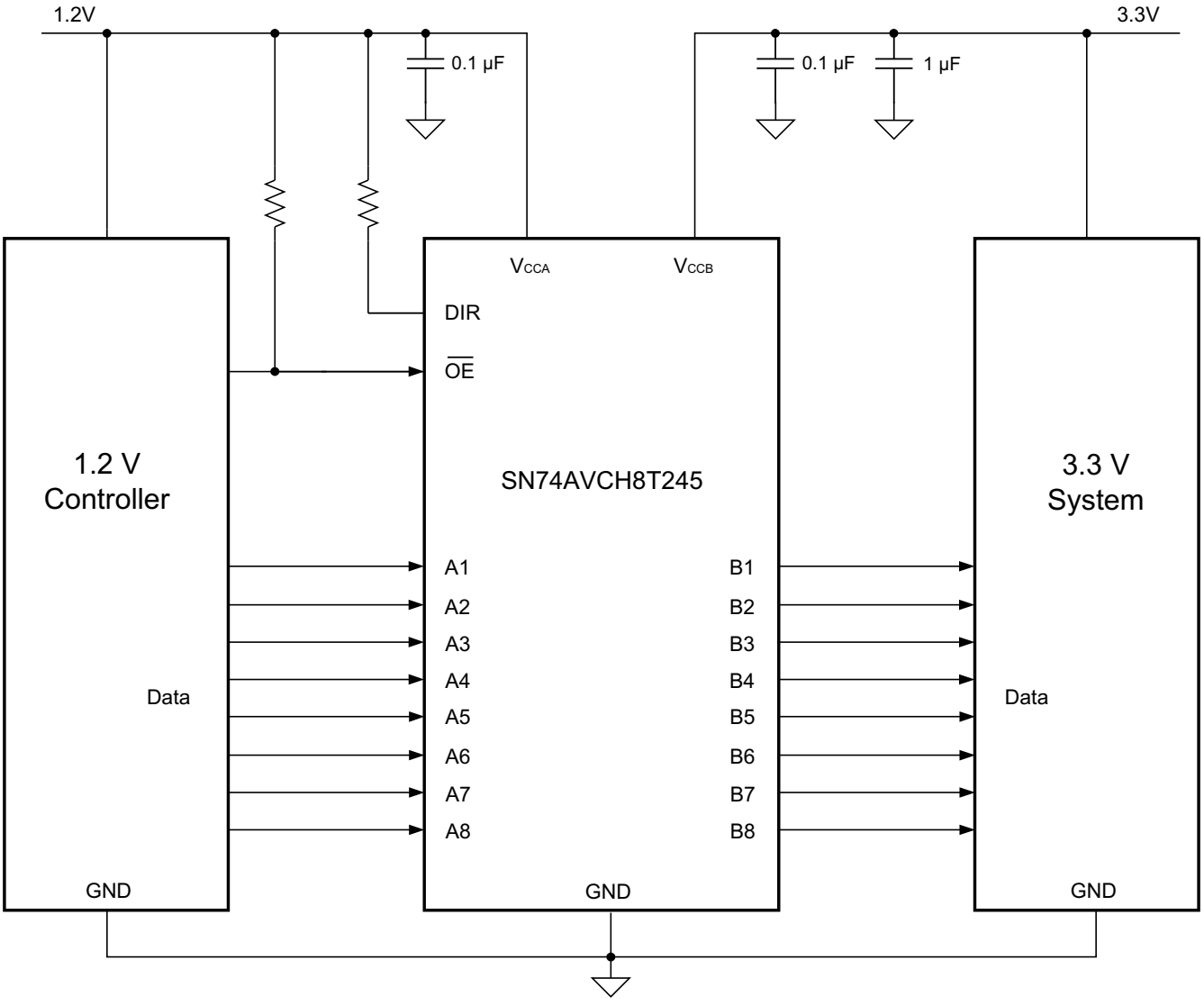

図 8-1. Typical Application Schematic

8.2.1 Design Requirements

For this design example, use the parameters listed in 表 8-1.

表 8-1. Design Parameters

DESIGN PARAMETERS	EXAMPLE VALUE
Input voltage	1.2V to 3.6V
Output voltage	1.2V to 3.6V

8.2.2 Detailed Design Procedure

To begin the design process, determine the following:

- Input voltage range:
  - Use the supply voltage of the device that is driving the SN74AVCH8T245 device to determine the input voltage range. For a valid logic high, the value must exceed the V_{IH} of the input port. For a valid logic low, the value must be less than the V_{IL} of the input port.
- Output voltage range:
  - Use the supply voltage of the device that the SN74AVCH8T245 device is driving to determine the output voltage range.

8.2.3 Application Curves

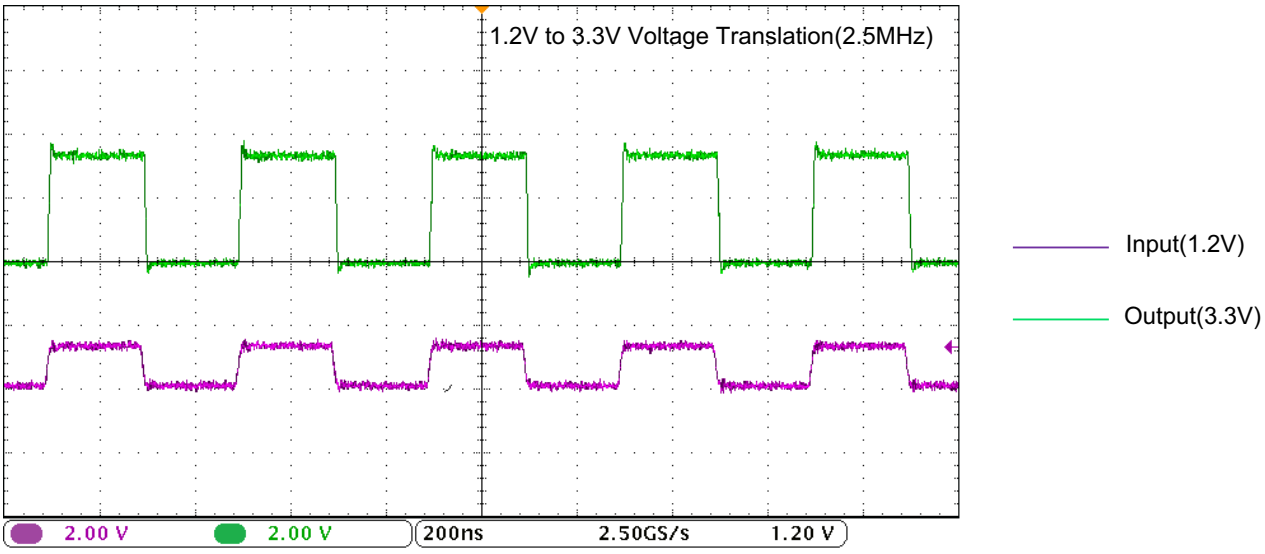

図 8-2. Translation Up (1.2V to 3.3V) at 2.5MHz

8.3 Power Supply Recommendations

The design of the output-enable ($\overline{OE}$) input circuit is referenced to VCCA so that all outputs are placed in the high-impedance state when the $\overline{OE}$ input is high. To put the outputs in a high-impedance state during power up or power down, the $\overline{OE}$ input pin must be tied to V_{CCA} through a pullup resistor and must not be enabled until V_{CCA} and V_{CCB} are fully ramped and stable. The current-sinking capability of the driver determines the minimum value of the pullup resistor to V_{CCA}.

V_{CCA} or V_{CCB} can be powered up first. If the SN74AVCH8T245 is powered up in a permanently enabled state (for example $\overline{OE}$ is always kept low), then pullup resistors are recommended at the input. Doing this allows for proper, glitch-free, power-up. For more information, see *Designing with SN4LVCXT245 and SN74LVCHXT245 Family of Direction Controlled Voltage Translators/Level-Shifters*. In addition, the $\overline{OE}$ pin may be shorted to GND if the application does not require use of the high-impedance state at any time.

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8.4 Layout

8.4.1 Layout Guidelines

For device reliability, TI recommends following the common printed-circuit board layout guidelines.

- Use bypass capacitors on power supplies.
- Use short trace lengths to avoid excessive loading.
- Placing pads on the signal paths for loading capacitors or pullup resistors to help adjust rise and fall times of signals depending on the system requirements.

8.4.2 Layout Example

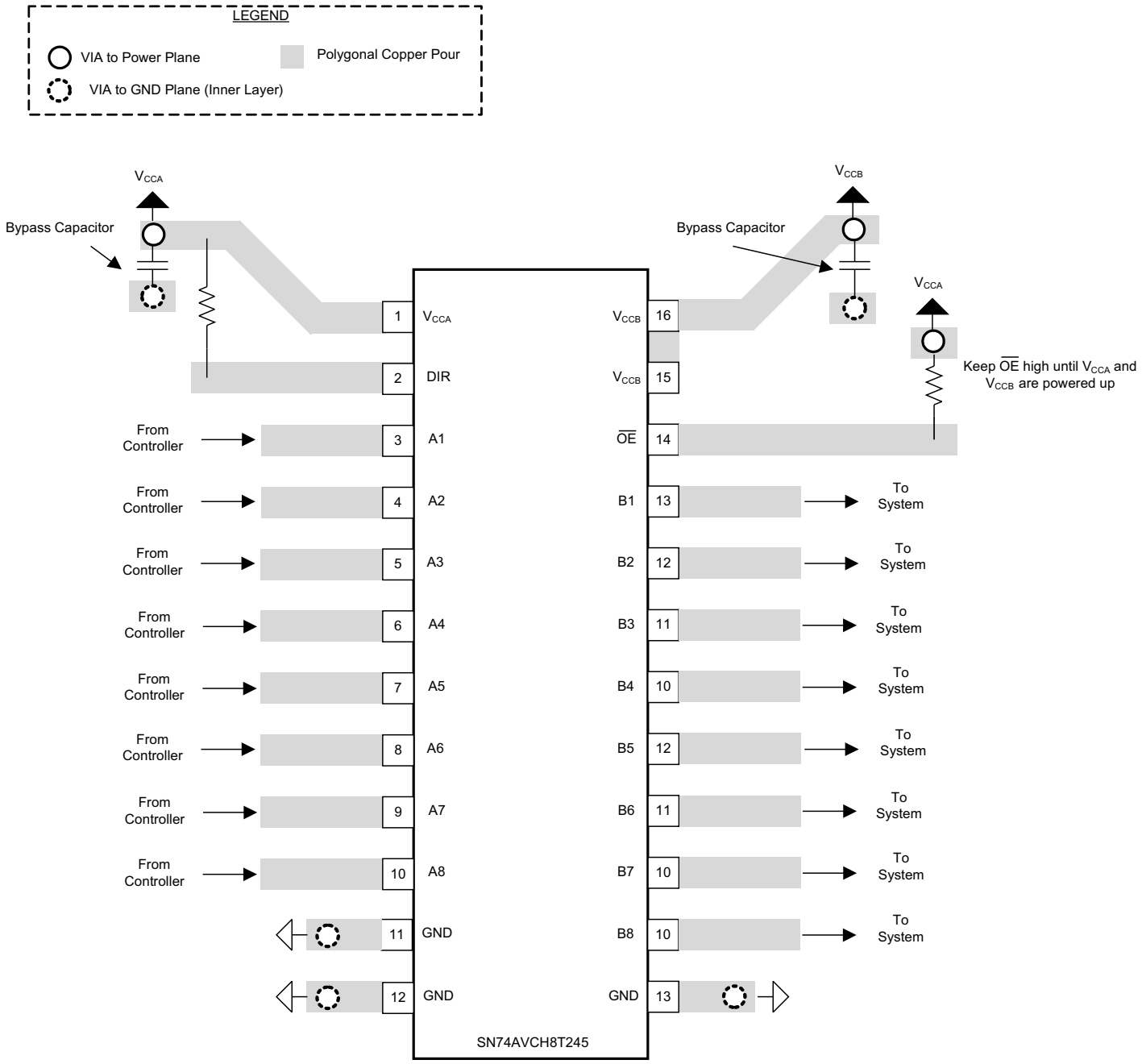

図 8-3. SN74AVCH8T245 Layout Example

9 Device and Documentation Support

9.1 Documentation Support

9.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, *Designing with SN74LVCXT245 and SN74LVCHXT245 Family of Direction Controlled Voltage Translators/Level-Shifters*
- Texas Instruments, *Bus-Hold Circuit*
- Texas Instruments, *AVC Logic Family Technology and Applications*
- Texas Instruments, *CMOS Power Consumption and Cpd Calculation*

9.2 ドキュメントの更新通知を受け取る方法

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10 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision I (November 2023) to Revision J (April 2024)	Page
• Changed kW to kΩ in the *Load Circuit and Voltage Waveforms* figure	16

Changes from Revision H (January 2016) to Revision I (November 2023)	Page
• ドキュメント全体にわたって表、図、相互参照の採番方法を更新	1
• パッケージ リード サイズを含めるよう「パッケージ情報」表を更新	1
• Updated the *Thermal Information* table for the *DGV*, *PW*, and *RHL* packages	6

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Changes from Revision G (March 2007) to Revision H (January 2016) **Page**

- 「ESD 定格」表、「機能説明」セクション、「デバイスの機能モード」セクション、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを追加。 1
- 「注文情報」表を削除 1

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
74AVCH8T245DGVRG4.A	Active	Production	TVSOP (DGV) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WP245
74AVCH8T245DGVRG4.B	Active	Production	TVSOP (DGV) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WP245
74AVCH8T245PWRG4	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WP245
74AVCH8T245RHLRG4	Active	Production	VQFN (RHL) | 24	1000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	WP245
SN74AVCH8T245DGVR	Active	Production	TVSOP (DGV) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WP245
SN74AVCH8T245DGVR.A	Active	Production	TVSOP (DGV) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WP245
SN74AVCH8T245DGVR.B	Active	Production	TVSOP (DGV) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WP245
SN74AVCH8T245PW	Active	Production	TSSOP (PW) | 24	60 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WP245
SN74AVCH8T245PW.B	Active	Production	TSSOP (PW) | 24	60 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WP245
SN74AVCH8T245PWG4	Active	Production	TSSOP (PW) | 24	60 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WP245
SN74AVCH8T245PWR	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WP245
SN74AVCH8T245PWR.A	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WP245
SN74AVCH8T245PWR.B	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WP245
SN74AVCH8T245RHLR	Active	Production	VQFN (RHL) | 24	1000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	WP245
SN74AVCH8T245RHLR.A	Active	Production	VQFN (RHL) | 24	1000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	WP245
SN74AVCH8T245RHLR.B	Active	Production	VQFN (RHL) | 24	1000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	WP245

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

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(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

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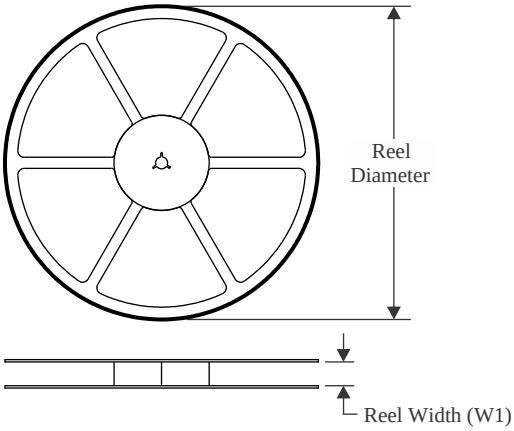
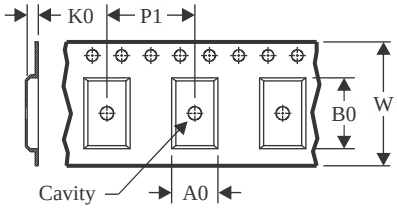
TAPE AND REEL INFORMATION

REEL DIMENSIONS

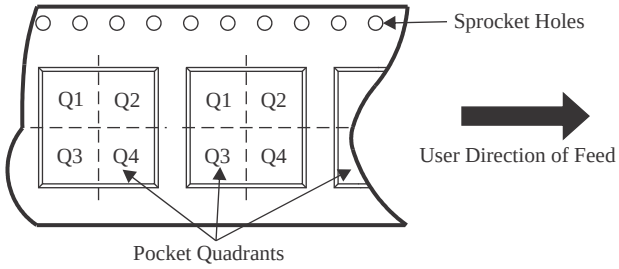


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

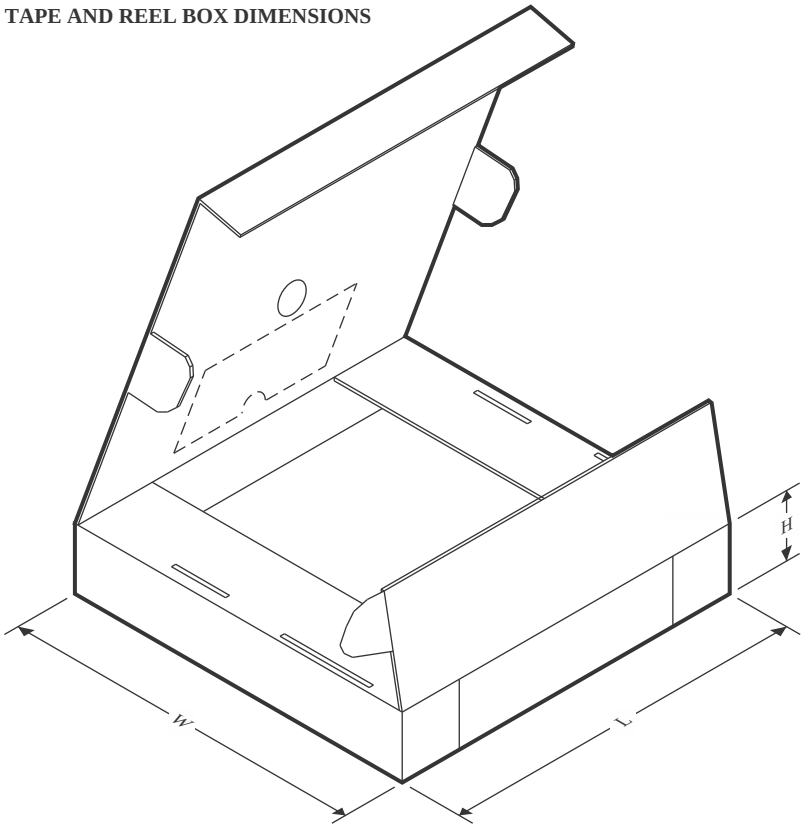
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AVCH8T245DGVR	TVSOP	DGV	24	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AVCH8T245PWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
SN74AVCH8T245RHLR	VQFN	RHL	24	1000	180.0	12.4	3.8	5.8	1.2	8.0	12.0	Q1

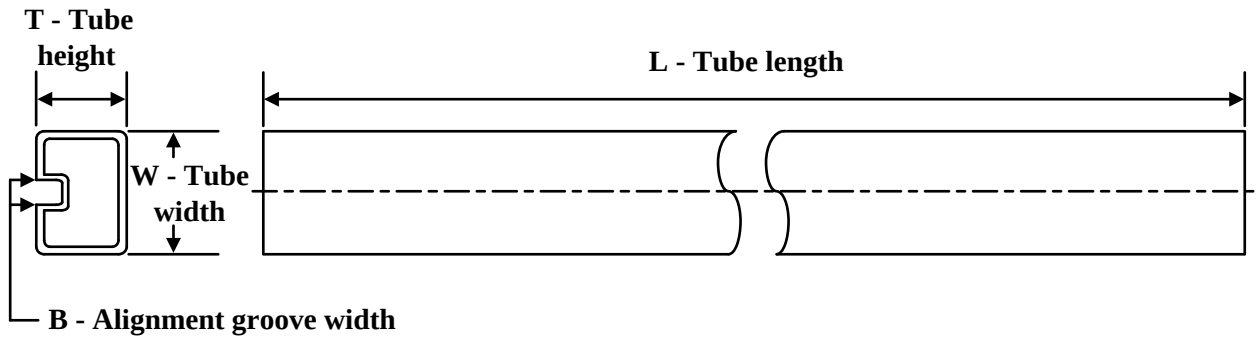
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AVCH8T245DGVR	TVSOP	DGV	24	2000	356.0	356.0	35.0
SN74AVCH8T245PWR	TSSOP	PW	24	2000	356.0	356.0	35.0
SN74AVCH8T245RHLR	VQFN	RHL	24	1000	210.0	185.0	35.0

TUBE



*All dimensions are nominal

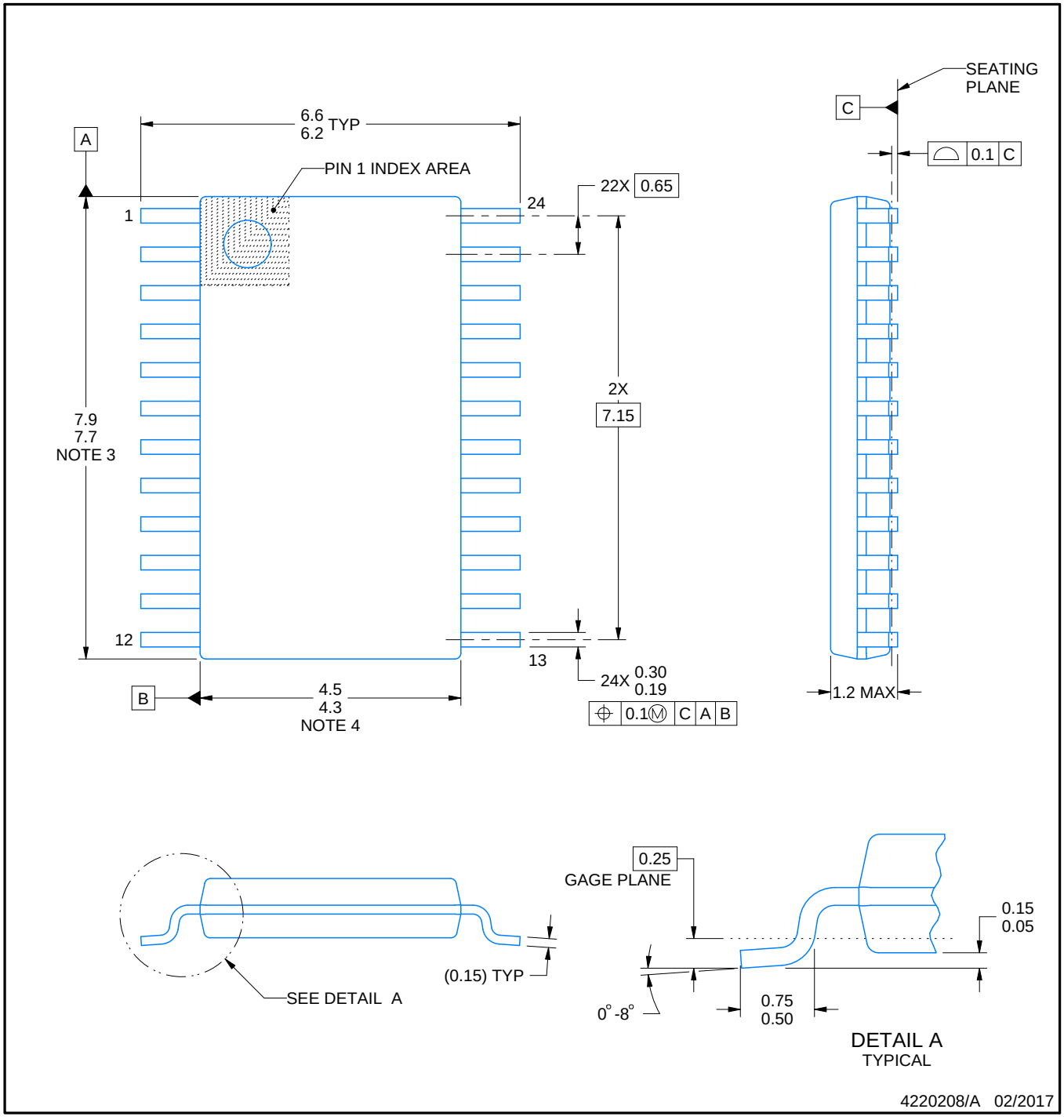
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74AVCH8T245PW	PW	TSSOP	24	60	530	10.2	3600	3.5
SN74AVCH8T245PW.B	PW	TSSOP	24	60	530	10.2	3600	3.5
SN74AVCH8T245PWG4	PW	TSSOP	24	60	530	10.2	3600	3.5

PACKAGE OUTLINE

PW0024A

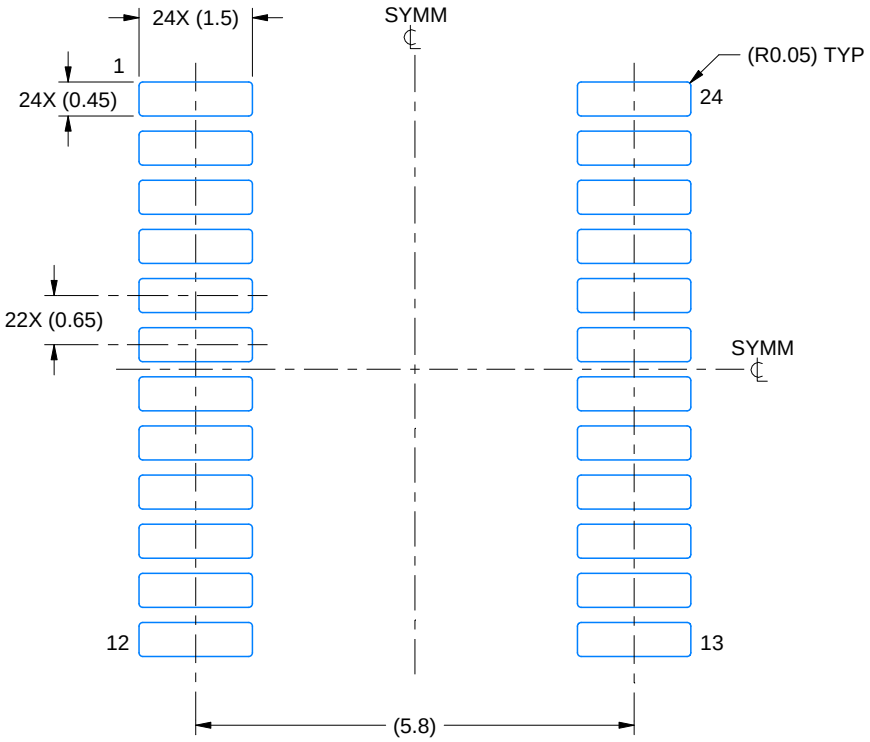
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

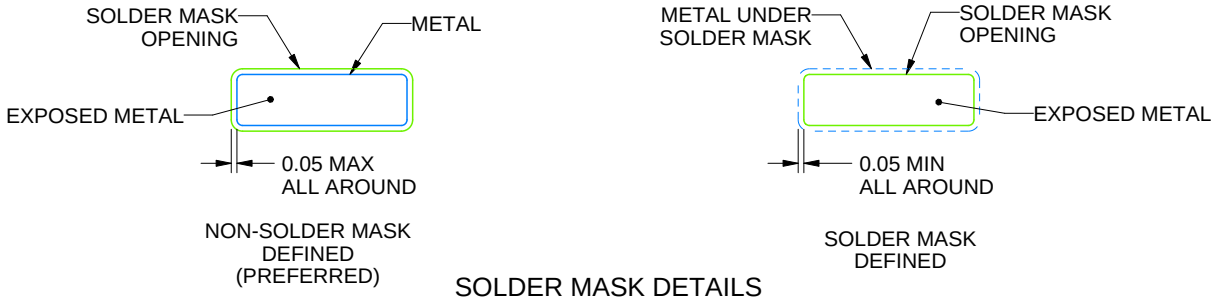


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

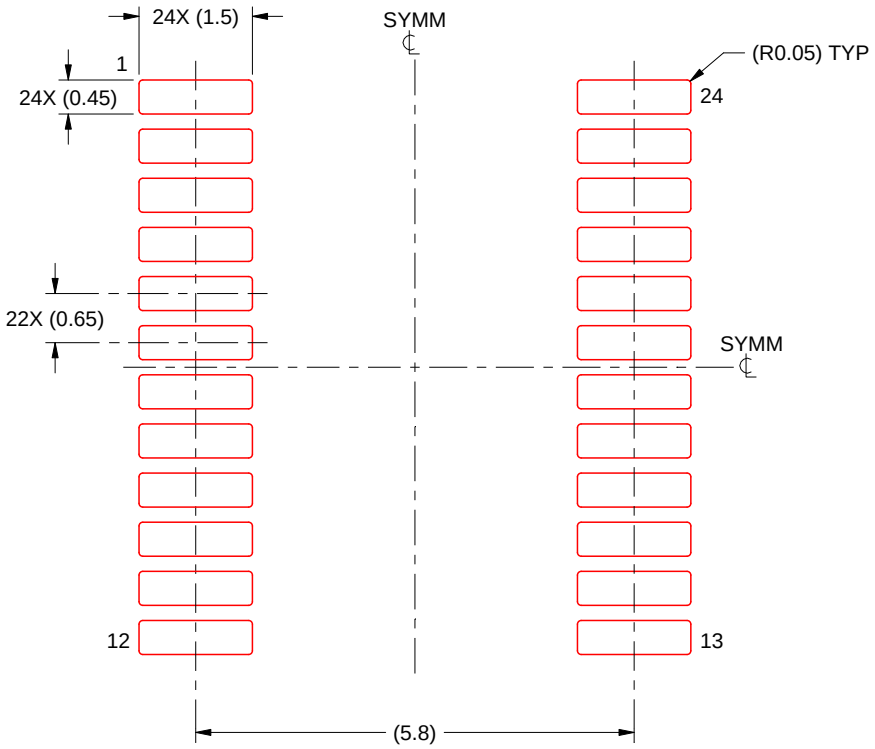


SOLDER MASK DETAILS

4220208/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220208/A 02/2017

NOTES: (continued)

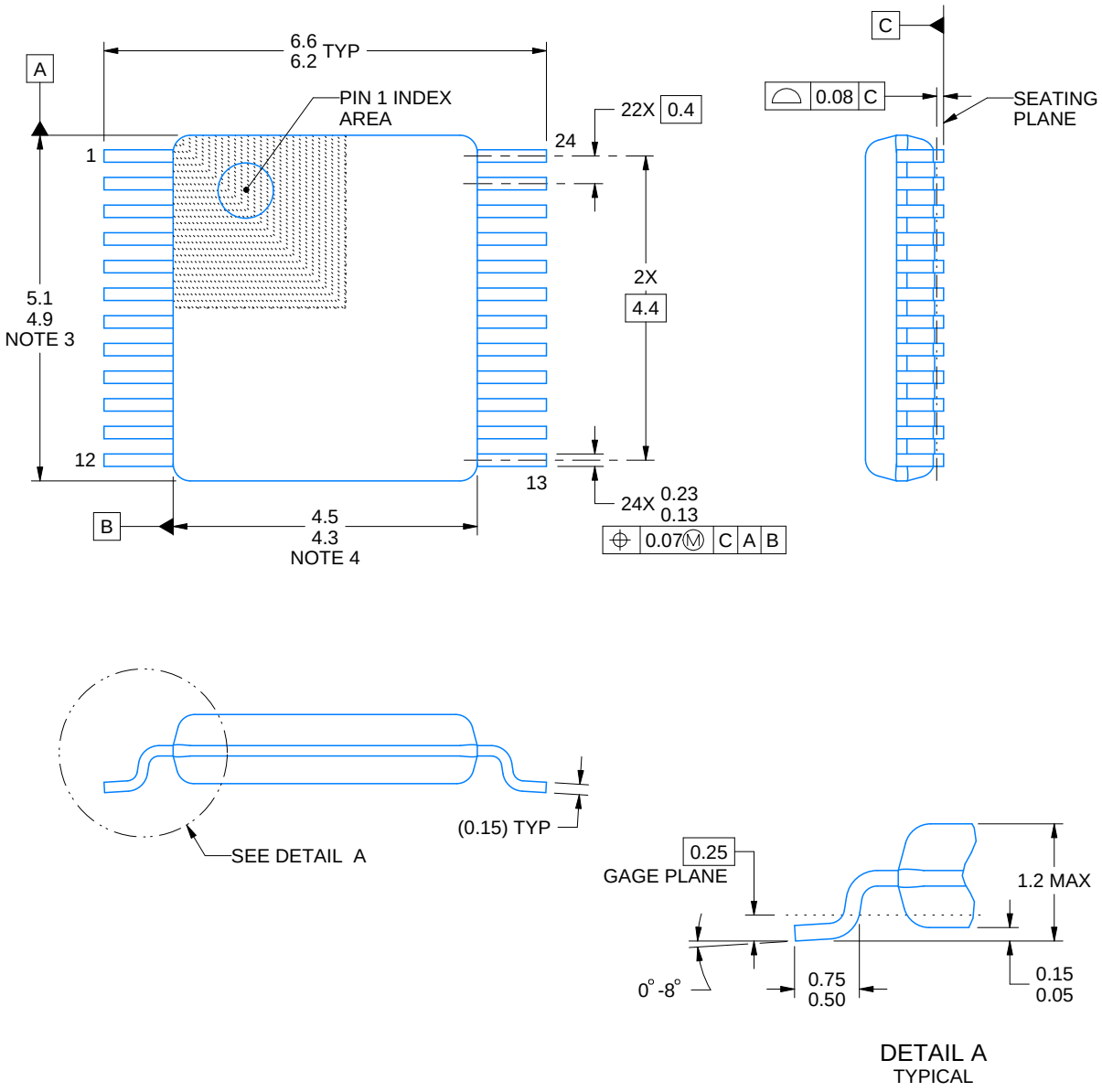
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

DGV0024A

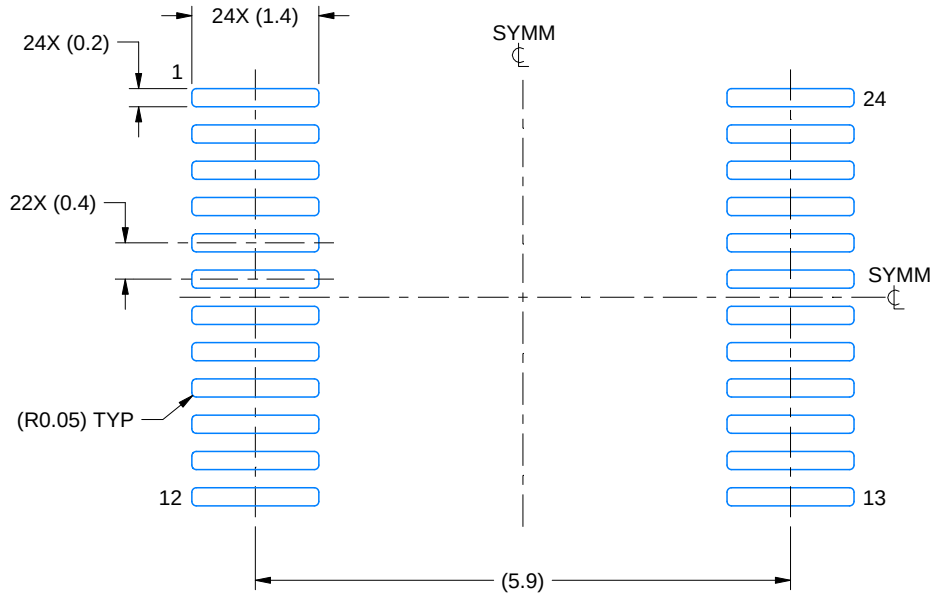
TVSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

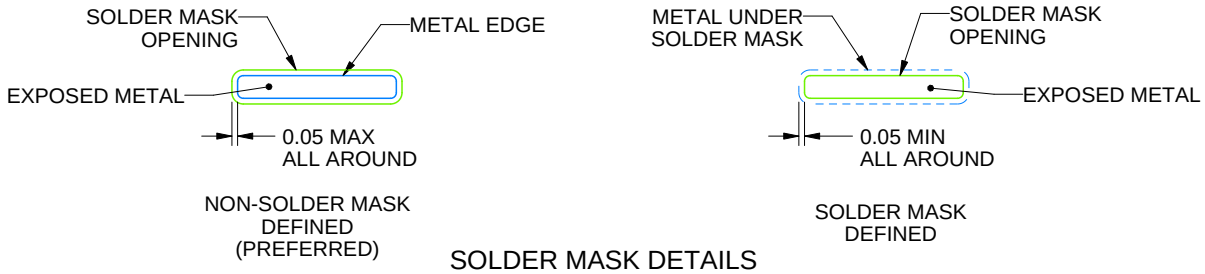


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 12X

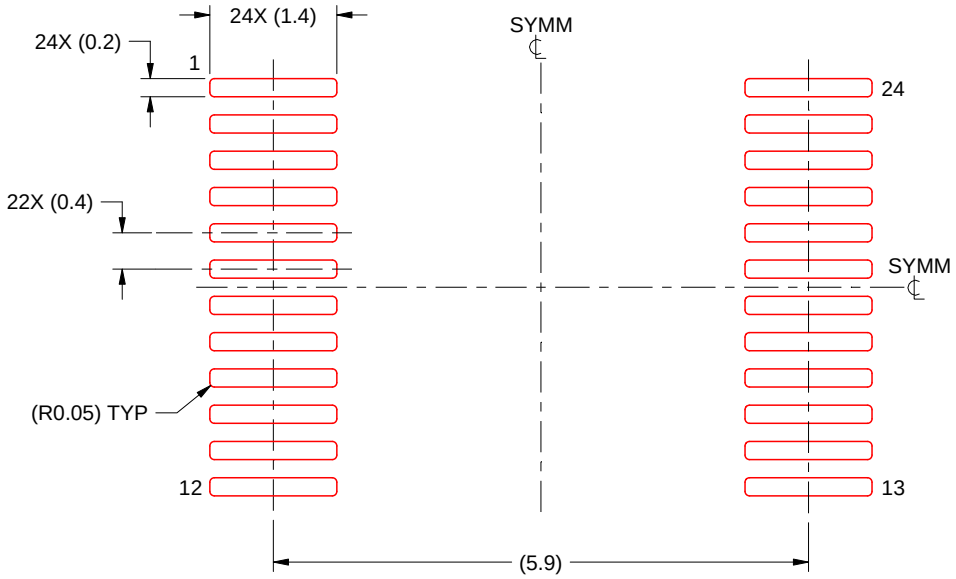


SOLDER MASK DETAILS

4229221/A 12/2022

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 12X

4229221/A 12/2022

NOTES: (continued)

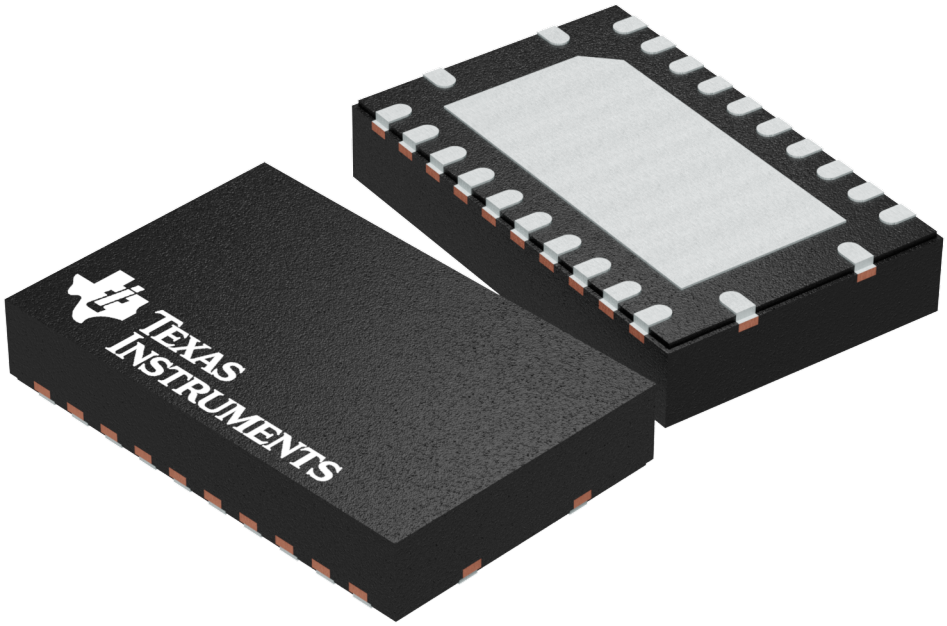
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

RGY 24

VQFN - 1 mm max height

5.5 x 3.5 mm, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD



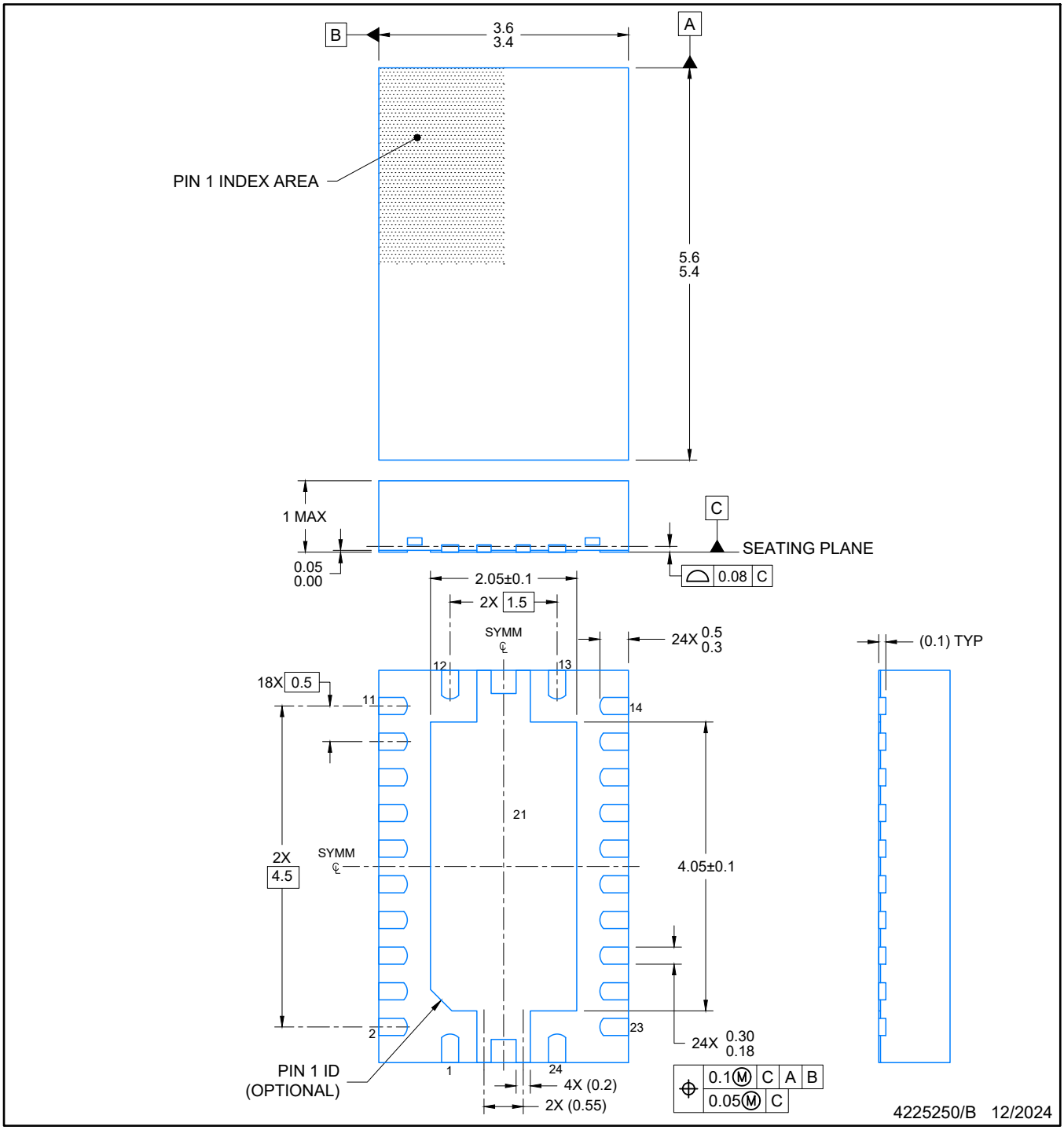
Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

PACKAGE OUTLINE

RHL0024A

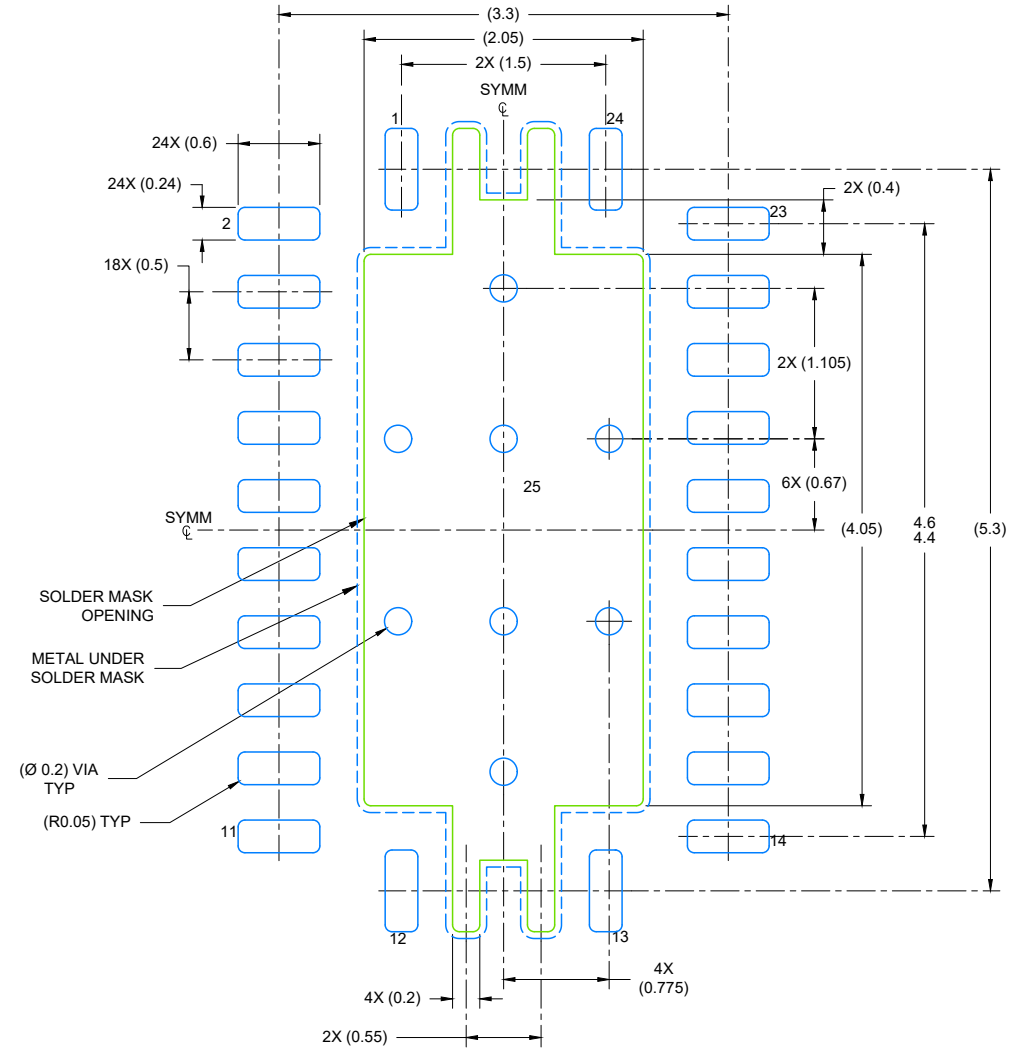
VQFN - 1 mm max height

PLASTIC QUAD FLATPACK- NO LEAD

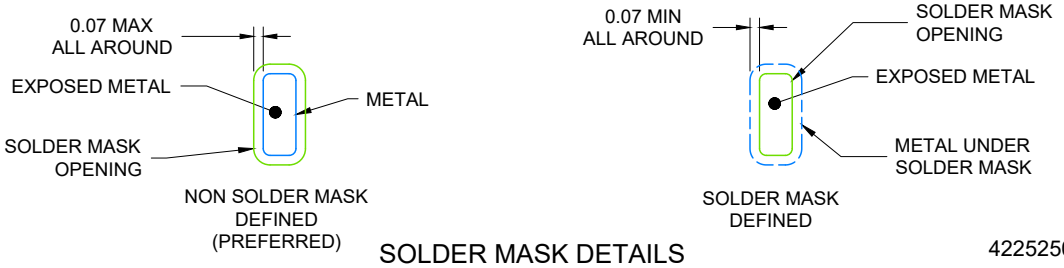


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 18X

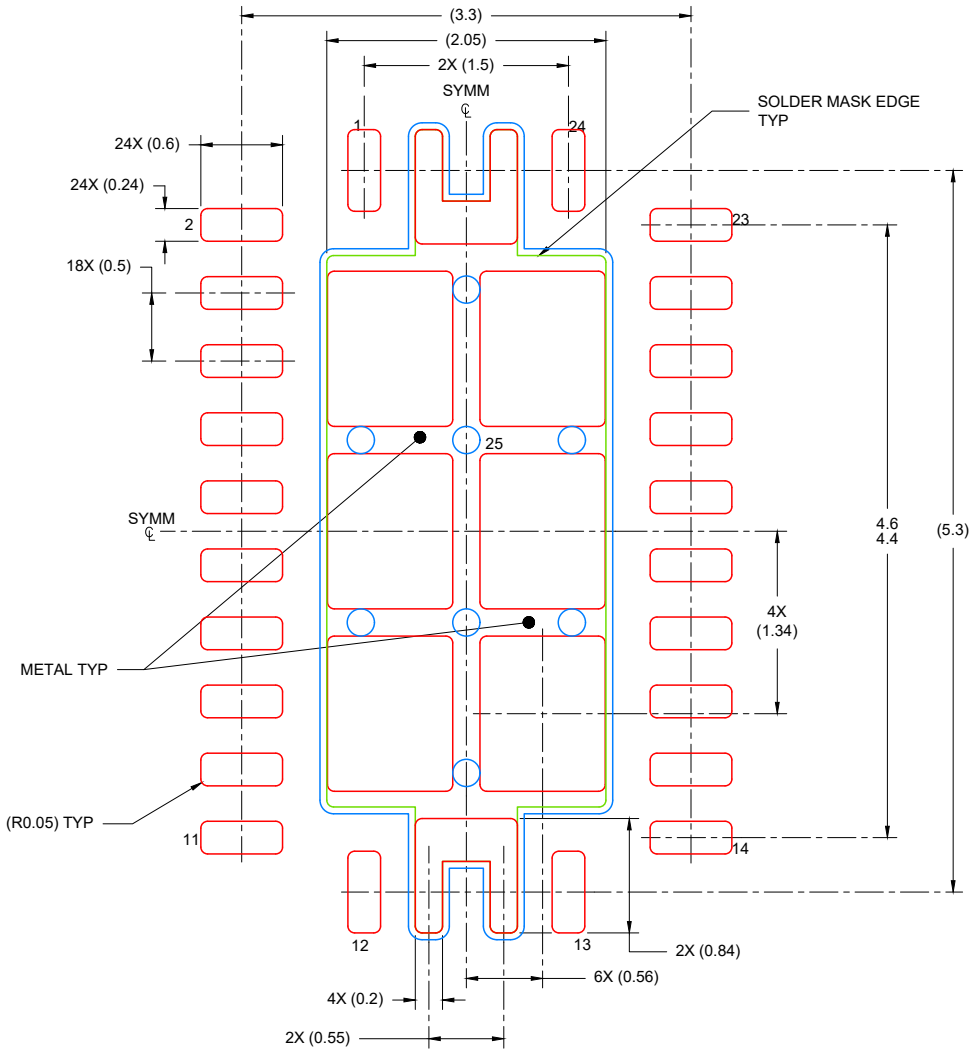


SOLDER MASK DETAILS

4225250/B 12/2024

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271) .
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
80% PRINTED COVERAGE BY AREA
SCALE: 18X

4225250/B 12/2024

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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